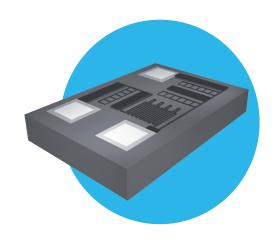
Resistors

Wire Bondable Voltage **Divider Network**

DSOT Series

- Tight TCR tracking
- **Extremely small footprint**
- Precision ratio tolerances to ±0.05%
- Ultra-stable tantalum nitride resistors





All parts are Pb-free and comply with EU Directive 2011/65/EU amended by (EU) 2015/863 (RoHS3)

IRC's TaNSil® voltage divider networks are ideally suited for low cost divider applications that demand precision performance in a wire

The tantalum nitride film system on silicon provides precision tolerance, exceptional TCR tracking and miniature physical dimensions. Excellent performance in harsh, humid environments is a trademark of IRC's selfpassivating TaNSil® resistor film.

For applications requiring high performance voltage dividers in a miniature, wire bondable package, specify IRC DSOT wire bondable die.

Electrical Data

Resistance Range Each Resistor		10Ω to 200kΩ			
Resistance Range Each Package		20Ω to 400kΩ			
Absolute Tolerance		to ±0.1%			
Ratio Tolerance to F	to ±0.05%				
Absolute TCR	to ±25ppm/°C				
Tracking TCR	to ±5ppm/°C				
Element Power Rating		125mW @70°C			
Package Power Rating		250mW @ 70°C			
Rated Operating Volume (not to exceed \sqrt{P} x	100V				
Operating Temperat	-55°C to + 150°C				
Noise	<-30dB				
Substrate Material		Oxidized Silicon (10KÅ SiO ₂ minimum)			
Substrate Thicknes	0.0095″ ±0.001 (0.241mm ±0.025)				
Bond Pad	Aluminum	10KÅ minimum			
Metallization	Gold ¹	15KÅ minimum			
Backside	Silicon (gold available¹)				
Passivation	Silicon Dioxide or Silicon Nitride				
Note 1: Not recommended for new designs					

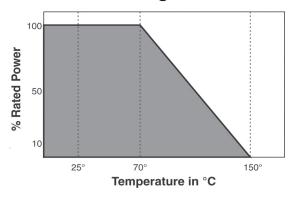
Note 1: Not recommended for new designs

TCR/Inspection Code Table

Absolute TCR	Commercial Code	MIL Inspection Code*
±300ppm/°C	00	04
±100ppm/°C	01	05
±50ppm/°C	02	06
±25ppm/°C	03	07

*Notes: Product supplied to Class H of MIL-PRF 38534 include 100% visual inspection

Power Derating Data



DSOT Series



Manufacturing Capabilities Data

Resistance Range	Available Absolute Tolerances	Available Ratio Tolerances	Best Absolute TCR	Tracking TCR
10Ω - 50Ω	FGJK	DFGJK	±100ppm/°C	±50ppm/°C
51Ω - 100Ω	DFGJK	CDFGJK	±100ppm/°C	±25ppm/°C
101Ω - 200Ω	CDFGJK	BCDFGJK	±50ppm/°C	±10ppm/°C
201Ω - 500Ω	BCDFGJK	BCDFGJK	±50ppm/°C	±5ppm/°C
501Ω - 400kΩ	BCDFGJK	ABCDFGJK	±25ppm/°C	±2ppm/°C

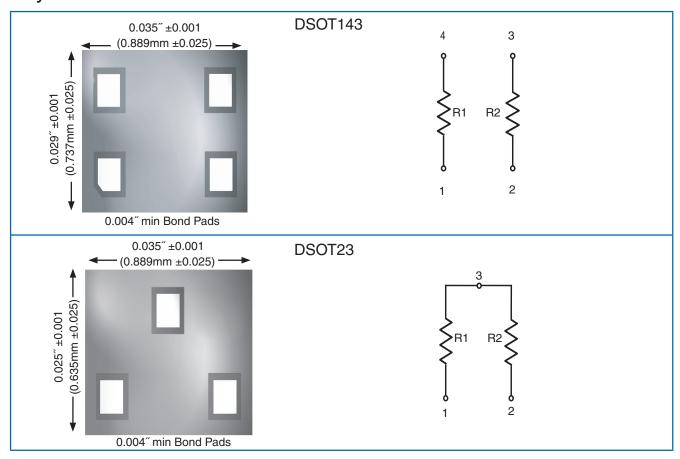
Environmental Data

Test	Method	Max ∆R	Typical ∆R
Thermal Shock	MIL-STD-202 Method 107 Test condition F	±0.1%	±0.02%
High Temperature Exposure	MIL-STD-883 Method 1008 150°C, 1000 hours	±0.1%	±0.05%
Low Temperature Shortage	-55°C, 1000 hours	±0.03%	±0.01%
Life	MIL-STD-202 Method 108 70°C, 1000 hours	±0.5%	±0.01%
Life at Elevated Temperature	MIL-STD-202 Method 108 125°C, 1000 hours	±0.5%	±0.05%

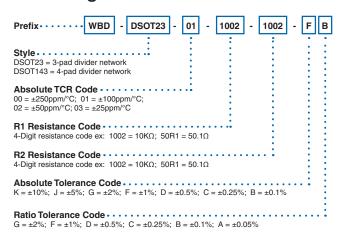




Physical Data



Ordering Data



Packaging

Standard packaging is 2" x 2" chip tray. For additional information or to discuss your specific requirements, please contact our Applications Team using the contact details below.